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Home > Products > Socket/Card Products > Product Feature Selector > Product Details

# 5050462-2 Product Details



5050462-2

Discrete Sockets

Always EU RoHS/ELV Compliant (Statement of Compliance)

#### Product Highlights:

- Mini-Spring Socket Product Line
- Board-to-Board, Wire-to-Board
- Applies To Wire/Cable, Applies To Printed Circuit Board
- Contact Rated Current = 5 A
- Wire/Cable Size = .081 .326 mm²

View all Features

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TE Internal Number: 5050462-2













#### Documentation & Additional Information

#### Product Drawings:

MINIATURE SPRING SOCKET ASSEMBLY SERIES 2 (PDF, English)

#### Catalog Pages/Data Sheets:

None Available

#### Product Specifications:

None Available

### Application Specifications:

None Available

#### Instruction Sheets:

None Available

### CAD Files: (CAD Format & Compression Information)

- 2D Drawing (DXF, Version 0)
- 3D Model (IGES, Version O)
- 3D Model (STEP, Version O)

#### Additional Information:

Product Line Information

#### Related Products:

Tooling



### Product Features (Please use the Product Drawing for all design activity)

# Product Type Features:

- Product Line = Mini-Spring Socket
- Socket Length (mm [in]) = 4.52 [0.178]
- Sleeve Style = Open Bottom
- Sealant = Without
- Wire/Cable Type = Discrete Wire
- Termination Method to Wire/Cable = Solder
- Termination Method to PC Board = Through Hole Press Fit
- Product Series = 3
- Sleeve Material = Copper
- Profile = Zero

#### Contact Type = Socket Contact Base Material = Beryllium Copper

List all Documents

Contact Features:

**Industry Standards:** Government/Industry Qualification = No.

Contact Spring Plating = Gold (30)

RoHS/ELV Compliance = RoHS compliant, ELV compliant

Contact Plating, Mating Area, Material = Gold (30)

• Lead Free Solder Processes = Wave solder capable to 260°C, Wave solder capable to 240°C, Wave solder capable to 265°C, Reflow solder capable to 245°C, Reflow solder capable to 260°C, Pin-in-Paste capable to 245°C, Pin-in-Paste capable to 260°C

Contact Plating, Mating Area, Thickness (μm [μin]) = 0.00076 [0.03]

RoHS/ELV Compliance History = Always was RoHS compliant

Operating Temperature (°C [°F]) = -65 - +126 [-85 - +258]

# Contact - Rated Current (A) = 5

**Electrical Characteristics:** 

# Termination Features:

- Wire/Cable Size (mm²) = 0.081 0.326
- Wire/Cable Size (AWG) = 22 28
- Insertion Method = Hand/Semi-Automatic

# Dimensions:

- Recommended Hole Size (mm [in]) = 1.32 [0.052]
- PCB Thickness, Recommended (mm [in]) = 0.79 3.18 [0.031 -0.125]

# Body Features:

- Mating Pin Dia. Range (mm [in]) = 0.36 0.66 [0.014 0.026]
- Sleeve Material Plating = Tin
- Wire Type = Solid
- Spring Material = Beryllium Copper

# Applies To = Wire/Cable, Printed Circuit Board

Conditions for Usage:

**Environmental:** 

# Operation/Application:

- Application Use = Board-to-Board, Wire-to-Board
- Contact Transmits (Typical Application) = Signal (Data)/Power
- Application = Production

# Packaging Features:

- Packaging Method = Loose Piece
- Packaging Quantity = 2,000/Bag

# Other:

Brand = AMP

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